

Accura® ClearVue™



Applications

- ▶ General purpose prototyping
- ▶ Models requiring high clarity
 - Headlamps and lenses
 - Fluid flow and visualisation models
 - Transparent assemblies
- ▶ Snapfits and complex assemblies
- ▶ Medical models and medical devices

Benefits

- ▶ The highest clarity and transparency
- ▶ Durable and strong
- ▶ Humidity and moisture stable
- ▶ USP class VI capable

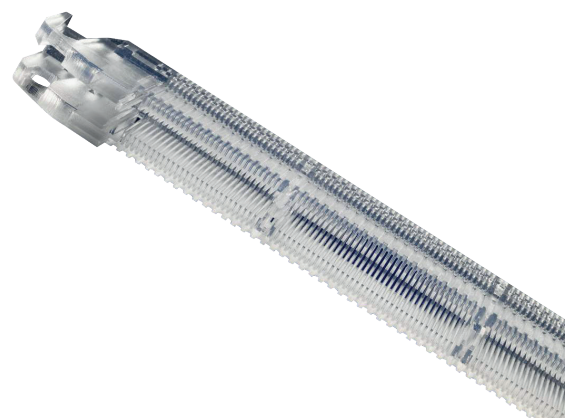


Technical data

MEASUREMENT	CONDITION	RESULT
Appearance		Clear/Transparent
Liquid Density	@ 25 °C (77 °F)	1.1 g/cm ³ at 25°C
Solid Density	@ 25 °C (77 °F)	1.17 g/cm ³ at 25°C
Viscosity	@ 30 °C (86 °F)	235-260 cps
Penetration Depth (Dp)		6.1 mils
Critical Exposure (Ec)		9.5 mJ/cm ²

Post-Cured Material

MEASUREMENT	CONDITION	METRIC	U.S.
Tensile Strength	ASTM D 638	46 - 53 MPa	6,700 - 7,700 PSI
Tensile Modulus	ASTM D 638	2,270 - 2,640 MPa	329 - 383 KSI
Elongation at Break (%)	ASTM D 638	3 - 15 %	3 - 15 %
Flexural Strength	ASTM D 790	72 - 84 MPa	10,400 - 12,200 PSI
Flexural Modulus	ASTM D 790	1,980 - 2,310 MPa	287- 335 KSI
Impact Strength (Izod Notched)	ASTM D 256	40 - 58 J/m	0.70 - 1.1 ft-lb/in
Heat Deflection Temperature	ASTM D 256		
	@ 66 PSI	51 °C	124 °F
	@ 264 PSI	50 °C	122 °F
Hardness, Shore D		80	80
Co-efficient of Thermal Expansion	ASTM E 831-93		
	@ 25-50 °C	122 µm/m-°C	68 µin/in-°F
	@ 50-100 °C	155 µm/m-°C	86 µin/in-°F
Glass Transition (Tg)	DMA, E''	62 °C	144 °F
Water Absorption	ASTM D 570-98	0.3%	0.3%



Warranty/Disclaimer: The performance characteristics of these products may vary according to product application, operating conditions, material combined with, or with end use. Prototype Projects makes no warranties of any type, express or implied, including, but not limited to, the warranties of merchantability or fitness for a particular use.

Please Note: All parts that are processed requiring USP Class VI must be cleaned and packaged following our guidelines, no post-processing operations can be carried out on these parts.

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